

#### **#** Product Features

- High Q
- High Power
- Low ESR/ESL
- Low Noise
- High Self-Resonance
- Ultra Stable Performance
- Capacitance Range: 0.1pF to 47pF
- Working Voltage: 50V

### **†** Product Applications

#### **Typical Functional Applications:**

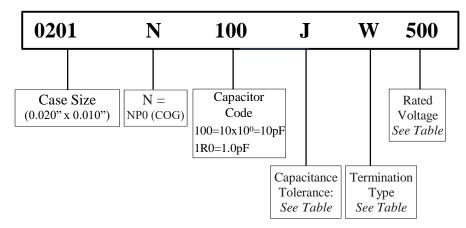
- Tuning Bypass Coupling
- Feedback D.C. Blocking
- Impedance Matching

#### **Typical Circuit Applications:**

- UHF/Microwave RF Power Amplifiers
- Mixers Oscillators Filter Networks
- Low Noise Amplifiers Timing Circuits and Delay Lines

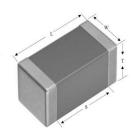


#### Part Numbering



### **‡** Capacitor Dimensions Unit: inch (millimeter)

Code	Term.	Length	Width	Thickness	Overlap	
		Lc	Wc	Tc	В	
W	Chip	$0.024 \pm 0.001$ $(0.60 \pm 0.03)$	$0.012 \pm 0.001 \\ (0.30 \pm 0.03)$	$0.012 \pm 0.001$ (0.30 ±0.03)	0.008 (0.20)	



## **†** Capacitance Tolerance Codes

Code	A	В	C	D	F	G	J	K
Tol.	±0.05pF	±0.1pF	±0.25pF	±0.5pF	±1%	±2%	±5%	±10%





 $0201N (0.020" \times 0.010")$ 

### **Terminations Type and Code**

Terminati Code	on	Termination
W	RoHS	100% Tin Solder over Nickel Barrier

## **≠** Voltage Codes

Voltage	Code
25V	250
50V	500



### 0201N Capacitance Values

For special capacitances, tolerances and WVDC, please contact PPI.

Cap.	Сар		Rated	WVDC	Cap.	Cap		Rated	WVDC	Cap.	Cap	- 1	Rated	WVD
pF	Code	Tol.	Std.	Ext.	pF	Code	Tol.	Std.	Ext.	pF	Code	Tol.	Std.	Ext.
0.1	OR1				2.2	2R2				16	160			
0.2	OR2				2.4	2R4			18	180				
0.3	OR3				2.7	2R7				20	200			
0.4	OR4				3.0	3R0	700202		25V 50V	22	220	F*,G,		501
0.5	OR5				3.3	3R3	A*,B, C,	25V		24	240		25V	50V
0.6	OR6				3.6	3R6	Ο,			27	270			
0.7	OR7				3.9	3R9				30	300			
0.8	OR8				4.3	4R3				33	330			
0.9	OR9		<b>4.7</b> 4R7			36	360							
1.0	1R0				5.1	5R1			39	390	0.11	251/	F0\/	
1.1	1R1	A*,B, C,	25V	50V	5.6	5R6				43	430	G,J,K	25V	50V
1.2	1R2	Ο,			6.2	6R2				47	470			
1.3	1R3				6.8	6R8	B,C,	25V	50V					
1.4	1R4				7.5	7R5								
1.5	1R5				8.2	8R2								
1.6	1R6				9.1	9R1								
1.7	1R7				10	100								
1.8	1R8				11	110	*****							
1.9	1R9				12	120	F*,G, J,K	25V	50V					
2.0	2R0				13	130	۸,۲	***************************************	A 1000 PC C C C C C C C C C C C C C C C C C					
2.1	2R1				15	150								

<sup>\*</sup>For A- & F-tolerance parts, contact factory for availability.





## **‡** Electrical Specifications

Quality Factor (Q)	2,000 at 1 MHz min.
Insulation Resistance (IR)	10 <sup>5</sup> Megaohms min. @ +25°C rated WVDC 10 <sup>4</sup> Megaohms min. @ +125°C rated WVDC
Rated Voltage	25V or 50V
Dielectric Withstanding Voltage (WVDC)	250% of Rated Voltage of 5 seconds
Operating Temperature Range	-55°C to 175°C
Temperature Coefficient (TC)	0±30ppm/°C
Capacitance Drift	±0.02% or ±0.02pF, whichever is greater
Piezoelectric Effects	None

## **=** Environmental Specifications

#### **Specification** Test Parameters

	-	
Thermal Shock	No mechanical damage  Capacitance Change: ±0.5% or 0.5pF max  IR: >10 G Ohms  Q>2000  Breakdown Voltage: 2.5x WVDC	MIL-STD-202, Method 107, Condition A. At the maximum rated temperature (-55°C and 175°C) stay 30 minutes, the time of removing shall not be more than 3 minutes. Perform five cycles.
Humidity (Steady State)	No mechanical damage  Capacitance Change: ±0.5% or 0.5pF max  IR: >1 G Ohms  Q>300  Breakdown Voltage: 2.5x WVDC	MIL-STD-202, Method 106
Low Voltage Humidity	No mechanical damage	MIL-STD-202, Method 103, Condition A, with 1.5 Volts DC applied while subjected to an environment of 85°C with 85% relative humidity for 240 hours minimum.
Life	No mechanical damage  Capacitance Change: ±2.0% or 0.5pF max  IR: >1 G Ohms  Q>500  Breakdown Voltage: 2.5x WVDC	MIL-STD-202, Method 108. For 1000 hours, at 175°C. 200% of Voltage for Capacitors
Terminal Adhesion	Termination should not pull off. Ceramic should remain undamaged	Linear pull force exerted on axial leads soldered to each terminal 2.0lbs.
Resistance to Soldering Heat	No mechanical damage  Capacitance Change: -1.0%~+2.0%  IR: >10 G Ohms  Q>500  Breakdown Voltage: 2.5x WVDC	Preheat device to 150°C -180°C for 60 seconds.  Dip in 260°C ±5°C solder for 10 ±1 second.  Measure after 24± 2 hour cooling period.

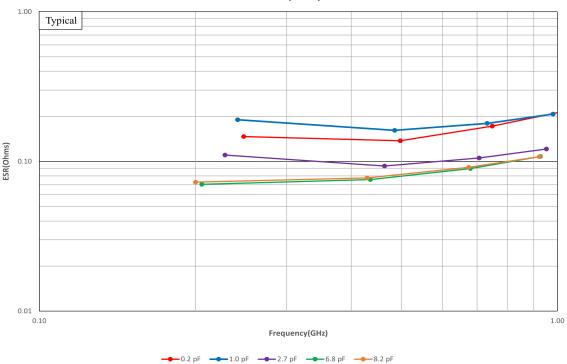
Capacitors are designed and manufactured to meet the requirements of MIL-PRF-55681 and MIL-PRF-123.



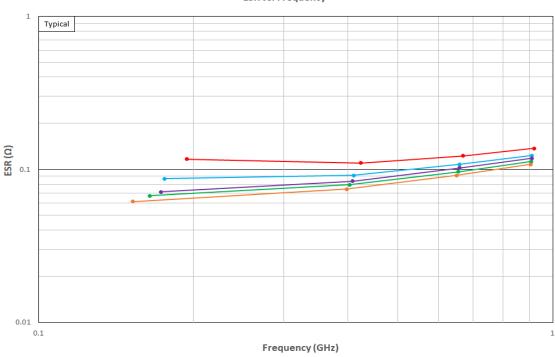


### # ESR vs. Frequency





#### ESR vs. Frequency

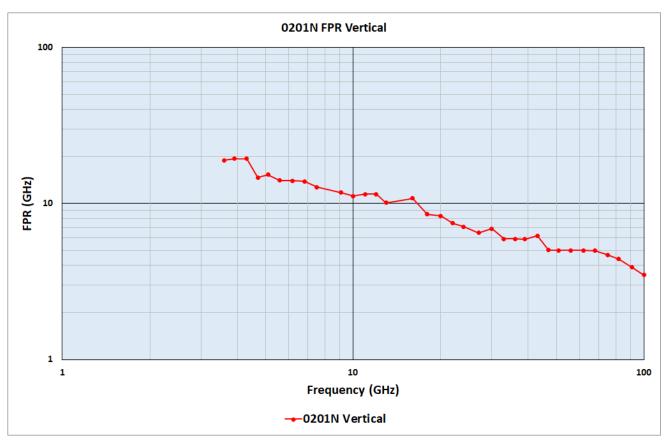


→ 10 pF → 18 pF → 20 pF → 27 pF → 47 pF





#### **First Parallel Resonance**



#### **Definitions** and Measurement Conditions

The **First Parallel Resonance**, **FPR**, is defined as the lowest frequency at which a suckout or notch appears in |S21|. It is generally independent of substrate thickness or dielectric constant, but does depend on capacitor orientation. A vertical orientation means the electrode planes are perpendicular to the substrate.

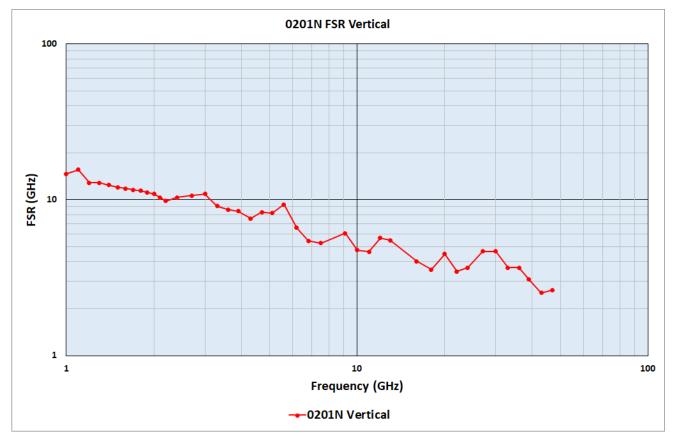
The definitions on the charts are for a capacitor in a series configuration, i.e., mounted across a gap in a microstrip trace with 50-Ohm termination. The measurement conditions are: substrate – Rogers RO3006; substrate dielectric constant = 6.15; substrate thickness (mils) = 10; gap in microstrip trace (mils) = 6.0; microstrip trace width (mils) = 14.1; Reference planes at sample edges.

All data has been derived from electrical models created by Modelithics, Inc., a specialty vendor contracted by PPI. The models are derived from measurements on a large number of parts disposed on several different substrates.





#### **First Series Resonance**



#### **Definitions** and Measurement Conditions

The **First Series Resonance**, **FSR**, is defined as the lowest frequency at which the imaginary part of the input impedance, Im[Zin], equals zero. Should Im[Zin] or the real part of the input impedance, Re[Zin], not be monotonic with frequency at frequencies lower than those at which Im[Zin] =0, the FSR shall be considered as undefined (represented as a gap in the plot). FSR is dependent on internal capacitor structure; substrate thickness and dielectric constant; capacitor orientation, as defined alongside the FPR plot; and mounting pad dimensions.

The definitions on the charts are for a capacitor in a series configuration, i.e., mounted across a gap in a microstrip trace with 50-Ohm termination. The measurement conditions are: substrate – Rogers RO3006; substrate dielectric constant = 6.15; substrate thickness (mils) = 10; gap in microstrip trace (mils) = 6.0; microstrip trace width (mils) = 14.1; Reference planes at sample edges.

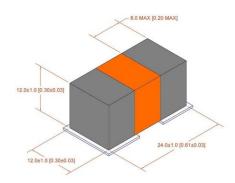
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#### **†** Capacitor Application Program

PPI's brand new online Capacitor Application Program (C.A.P.) helps Engineers and Designers select capacitors according to parameters such as cap value and frequency. C.A.P. allows engineers to insert capacitors requirements (Cap value, Frequency), producing Scattering Matrices (S2P) Charts while providing options (Case Size, Terminations, Mounting), and parameters (ESR, Q, Impedance) along with Datasheets. Once engineers have determined their capacitor requirements, C.A.P. also includes online Requests For Quotes (RFQs) and/or sample requests.



### **#** Modelithics Vendor Program

PPI offers design engineers a Free 90-Day Trial license for the Modelithics PPI Component Library. This program provides engineers access to extremely accurate scalable simulation models for Passive Plus capacitors with advanced features that enable a more precise and rapid design process.

Microwave Global Models include every part value in a series and permit users to input substrate thickness, dielectric constant, and loss tangent, as well as mounting pad layout dimensions. Selected models also include capacitor orientation – vertical or horizontal – as an input. Engineers can request FREE use of the models by visiting the https://www.modelithics.com/MVP/PPI.



#### **Recommended Land Pattern Dimensions**

Regarding Landing Patterns, please refer to IPC-7351B (table 3-5, 3-6).

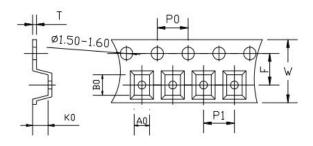




### **Tape & Reel Specifications** Dimensions: mm

Orientation	Measurement Unit	W	P0	P1	Т	F	Minimum Qty per Reel	Std Qty per Reel	Tape Material
Н	in. mm	0.315 8.00	0.157 4.00	0.079 2.00	0.017 0.42	0.138 3.50	1000	15000	Paper





#### $A_0B_0K_0$

- Determined by component size. Typical clearance between the cavity and the component is: .50 (.002) min to .65 (.026) max for 12mm tape.
- The component cannot rotate more than 20° within the determined cavity.

### **=** Engineering Design Kits

PPI offers Design Kits for engineers who are building and testing prototypes. Each kit contains 10 pieces per value.

Kits are 100% RoHS compliant.

Kit Number	Value Range	Values	
DKD0201N01	0.1 - 2.0pF	0.1, 0.2, 0.3, 0.5, 0.7, 0.8, 0.9, 1.0, 1.3, 1.5, 1.7, 1.9, 2.0pF	RoHS
DKD0201N02	1.0 - 10pF	1.0, 1.3, 1.5, 1.7, 1.9, 2.0, 2.2, 2.7, 3.0, 3.9, 4.7, 5.6, 6.8, 7.5, 8.2, 10pF	RoHS
DKD0201N03	10 - 47pF	10, 13, 15, 18, 20, 22, 27, 30, 39, 47pF	1







